General Purpose ABS, POLYLAC® PA-757F

Processing Conditions

A. Pre-drying  80 ~ 85 °C x 2 ~ 4 hrs
   depending on  a) Humidity
   b) Ratio of reground resin
   c) Storage conditions

B. Barrel Setting Profile

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MAX (°C)  230  230  220
MIN (°C)  190  190  180
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C. Mold Temperature  30~70°C
   depending on  a) Thickness
   b) Dimension
   c) Gate and runner system

NOTE :

1. Keep the resin from dust and contamination during handling and production.
2. Do not retain the hot melt at the barrel for a long time between injection cycles.
3. Temperature setting of manifold system should not exceed 240°C to avoid melt from degraded.

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